

1 Characteristics

Table 1. Standards compliance

Standard	Peak surge voltage (V)	Voltage waveform	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard (Ω)	
GR-1089 Core First level	2500	2/10 μ s	500	2/10 μ s	12	
	1000	10/1000 μ s	100	10/1000 μ s	24	
GR-1089 Core Second level	5000	2/10 μ s	500	2/10 μ s	24	
GR-1089 Core Intra-building	1500	2/10 μ s	100	2/10 μ s	0	
ITU-T-K20/K21	6000	10/700 μ s	150	5/310 μ s	110	
	1500		37.5		0	
ITU-T-K20 (IEC 61000-4-2)	8000	1/60 ns	ESD contact discharge ESD air discharge		0	
	15000				0	
IEC 61000-4-5	4000	10/700 μ s	100	5/310 μ s	60	
	4000	1.2/50 μ s	100	8/20 μ s	0	
TIA-968-A, lightning surge type A	1500	10/160 μ s	200	10/160 μ s	22.5	
	800	10/560 μ s	100	10/560 μ s	15	
TIA-968-A, lightning surge type B	1000	9/720 μ s	25	5/320 μ s	0	

Table 2. Thermal resistances

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient	120	$^{\circ}\text{C/W}$

Table 3. Absolute ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
I_{PP}	Peak pulse current	10/1000 μs	30
		8/20 μs	100
		10/560 μs	35
		5/310 μs	40
		10/160 μs	50
		1/20 μs	100
		2/10 μs	150
I_{TSM}	Non repetitive surge peak on-state current (50 Hz sinusoidal)	$t = 20\text{ ms}$	18
		$t = 200\text{ ms}$	10
		$t = 1\text{ s}$	7
V_{Gn}	Negative battery voltage range	$-40\text{ }^{\circ}\text{C} < T_{amb} < +85\text{ }^{\circ}\text{C}$	-175
T_{stg}	Storage temperature range		-55 to +150
T_j	Operating junction temperature range		-40 to +150
T_L	Maximum lead temperature for soldering during 10 s.		260

Figure 2. Electrical characteristics (definitions)

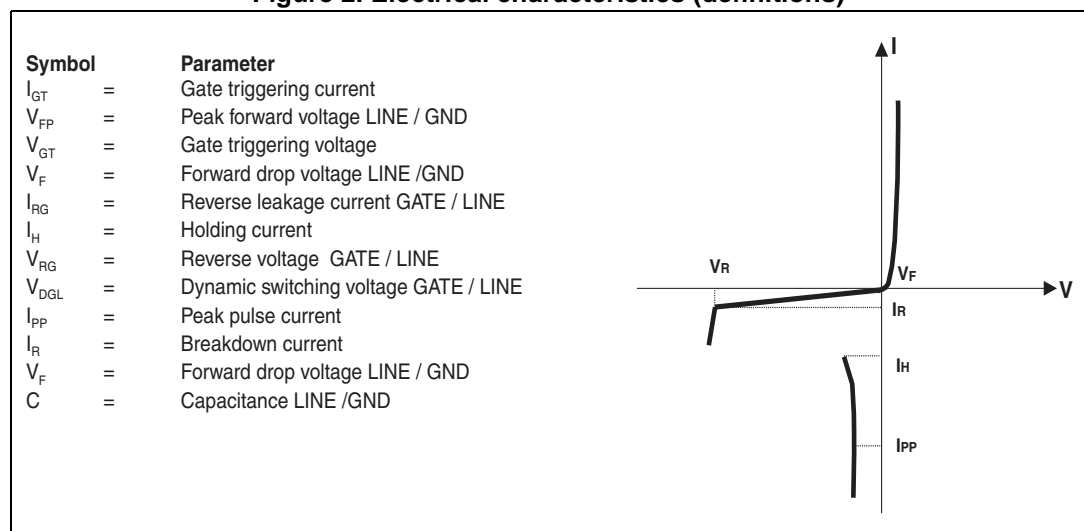


Figure 3. Pulse waveform

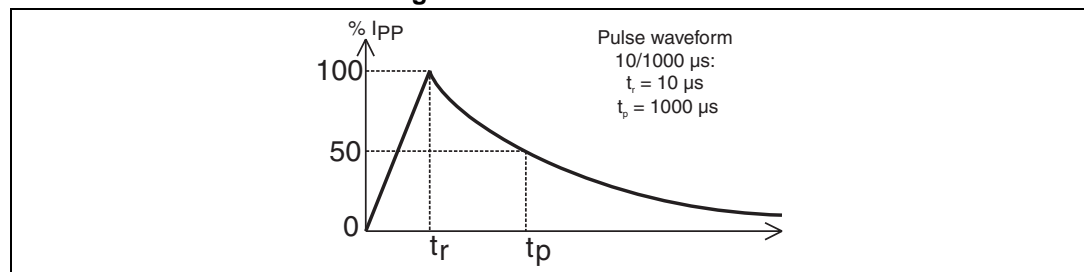


Table 4. Parameters related to the diode LINE / GND ($T_{amb} = 25\text{ °C}$)

Symbol	Test conditions			Max.	Unit
V_F	$I_F = 5\text{ A}$		$t = 500\text{ }\mu\text{s}$	3	V
V_{FP}	10/700 μs	1.5 kV	$R_S = 10\text{ }\Omega$	5	V
	1.2/50 μs	1.5 kV	$R_S = 10\text{ }\Omega$	9	
	2/10 μs	2.5 kV	$R_S = 62\text{ }\Omega$	30	

Table 5. Parameters related to the protection thyristors ($T_{amb} = 25\text{ °C}$)

Symbol	Test conditions				Min.	Max.	Unit
I _{GT}	V _{LINE} = -48 V				0.1	5	mA
I _H	V _{Gn} = -48 V				150		mA
V _{GT}	at I _{GT}					2.5	V
I _{RG}	V _{RG} = -175 V		T _j = 25 °C			5	μA
	V _{RG} = -175 V		T _j = 85 °C			50	
V _{DGL}	V _{Gn} = -48 V ⁽¹⁾						V
	10/700 μs	1.5 kV	R _S = 10 Ω	I _{PP} = 30 A		7	
	1.2/50 μs	1.5 kV	R _S = 10 Ω	I _{PP} = 30 A		10	
	2/10 μs	2.5 kV	R _S = 62 Ω	I _{PP} = 38 A		25	

1. The oscillations with a time duration lower than 50 ns are not taken into account.

Table 6. Parameters related to diode and protection thyristors ($T_{amb} = 25\text{ °C}$)

Symbol	Test conditions			Typ.	Max.	Unit
I_R	$V_{Gn} / LINE = -1\text{ V}$	$V_{LINE} = -175\text{ V}$	$T_j = 25\text{ °C}$		5	μA
	$V_{Gn} / LINE = -1\text{ V}$	$V_{LINE} = -175\text{ V}$	$T_j = 85\text{ °C}$		50	
C	$V_{LINE} = -50\text{ V}, V_{RMS} = 1\text{ V}, F = 1\text{ MHz}$			15		pF
	$V_{LINE} = -2\text{ V}, V_{RMS} = 1\text{ V}, F = 1\text{ MHz}$			35		

Table 7. Recommended gate capacitance

Symbol	Component	Min.	Typ.	Max.	Unit
C_G	Gate decoupling capacitance	100	220		nF

2 Technical information

Figure 4. LCP concept behavior

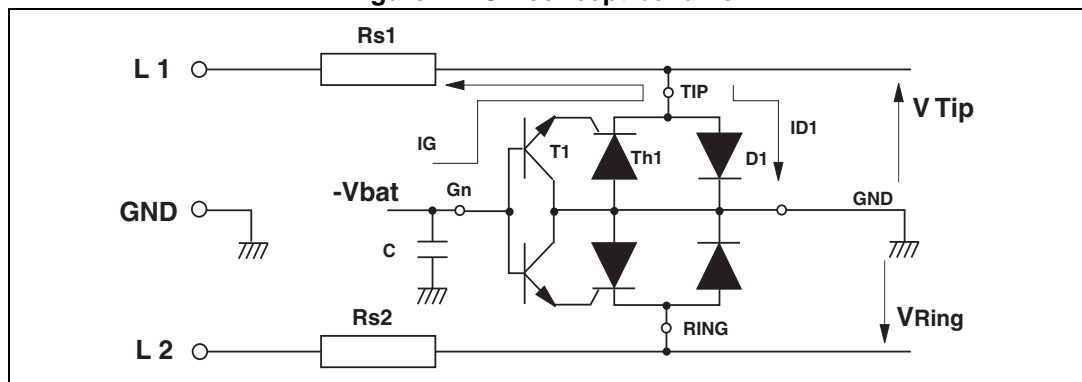


Figure 4 shows the classical protection circuit using the LCP crowbar concept. This topology has been developed to protect the new high voltage SLICs. It allows to program the negative firing threshold while the positive clamping value is fixed at GND.

When a negative surge occurs on one wire (L1 for example) a current I_G flows through the base of the transistor T1 and then injects a current in the gate of the thyristor Th1. Th1 fires and all the surge current flows through the ground. After the surge when the current flowing through Th1 becomes less negative than the holding current I_H , then Th1 switches off.

When a positive surge occurs on one wire (L1 for example) the diode D1 conducts and the surge current flows through the ground.

Figure 5. Example of PCB layout based on LCP1521S protection

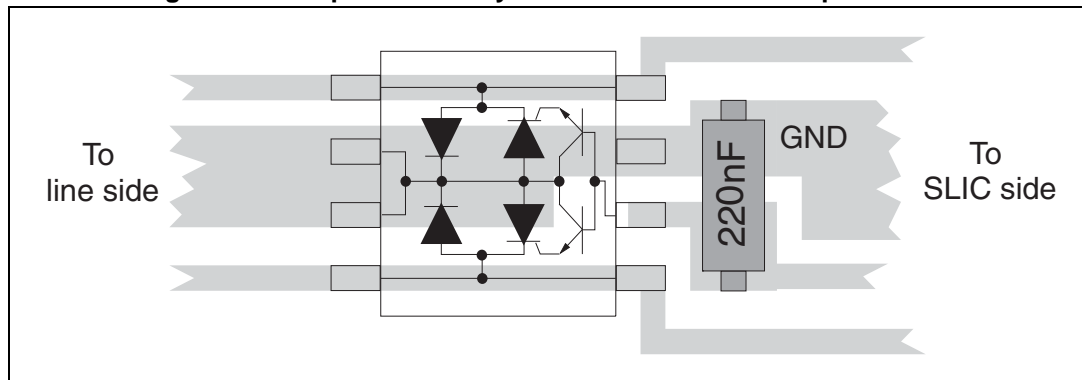


Figure 5 shows the classical PCB layout used to optimize line protection.

The capacitor C is used to speed up the crowbar structure firing during the fast surge edges.

This allows minimization of the dynamic breakover voltage at the SLIC Tip and Ring inputs during fast strikes. Note that this capacitor is generally present around the SLIC - Vbat pin.

So to be efficient it has to be as close as possible from the LCP Gate pin and from the reference ground track (or plan) (see Figure 5). The optimized value for C is 220 nF.

The series resistors Rs1 and Rs2 designed in [Figure 4](#) represent the fuse resistors or the PTC which are mandatory to withstand the power contact or the power induction tests imposed by the various country standards. Taking into account this fact the actual lightning surge current flowing through the LCP is equal to:

$$I_{\text{surge}} = V_{\text{surge}} / (R_g + R_s)$$

With:

V_{surge} = peak surge voltage imposed by the standard.

R_g = series resistor of the surge generator

R_s = series resistor of the line card (e.g. PTC)

e.g. For a line card with 30 Ω of series resistors which has to be qualified under GR1089 core 1000V 10/1000 μ s surge, the actual current through the LCP is equal to:

$$I_{\text{surge}} = 1000 / (10 + 30) = \mathbf{25\text{ A}}$$

The LCP is particularly optimized for the new telecom applications such as the fiber in the loop, the WLL, the remote central office. In this case, the operating voltages are smaller than in the classical system. This makes the high voltage SLICs particularly suitable.

The schematics of [Figure 6](#) give the most frequent topology used for these applications.

Figure 6. Protection of high voltage SLIC

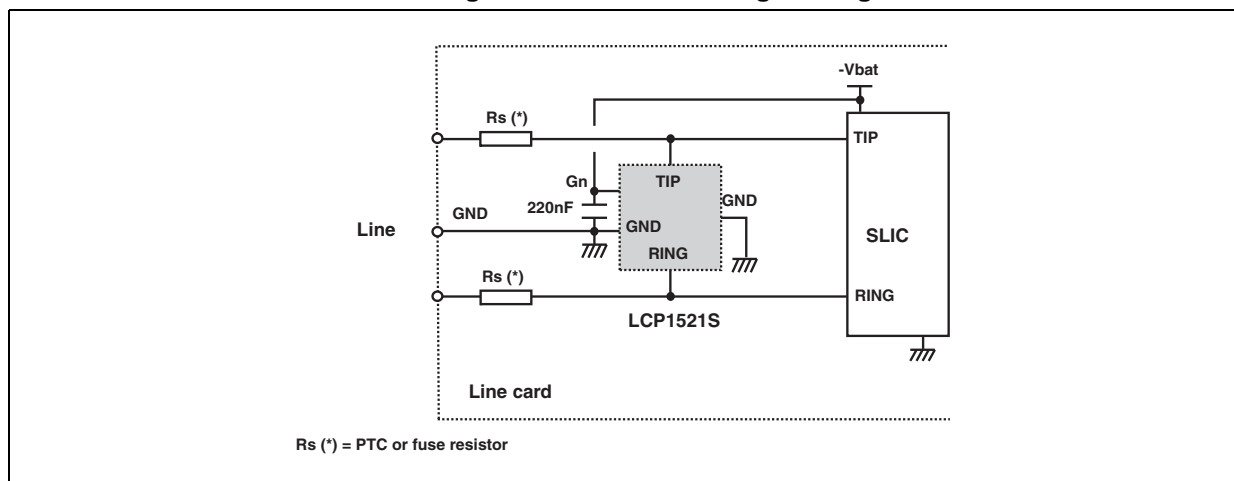


Figure 7. Surge peak current versus overload duration

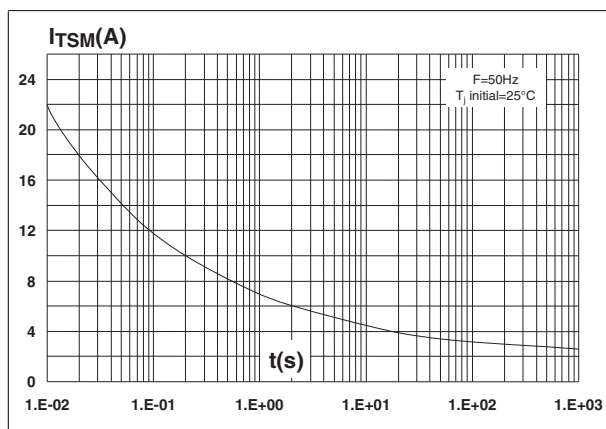
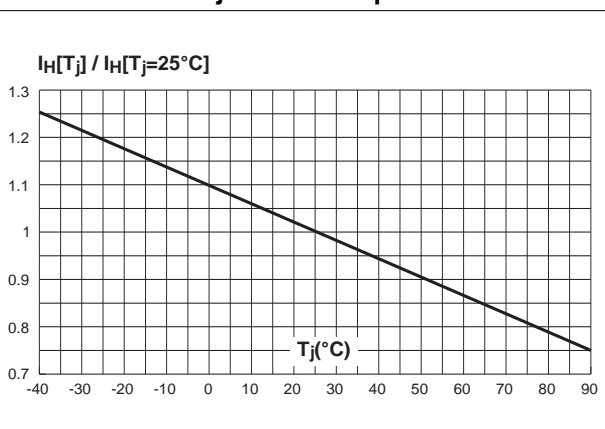


Figure 8. Relative variation of holding current versus junction temperature



3 Package information

- Epoxy meets UL94, V0
- Lead-free packages

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Figure 9. SO-8 dimension definitions

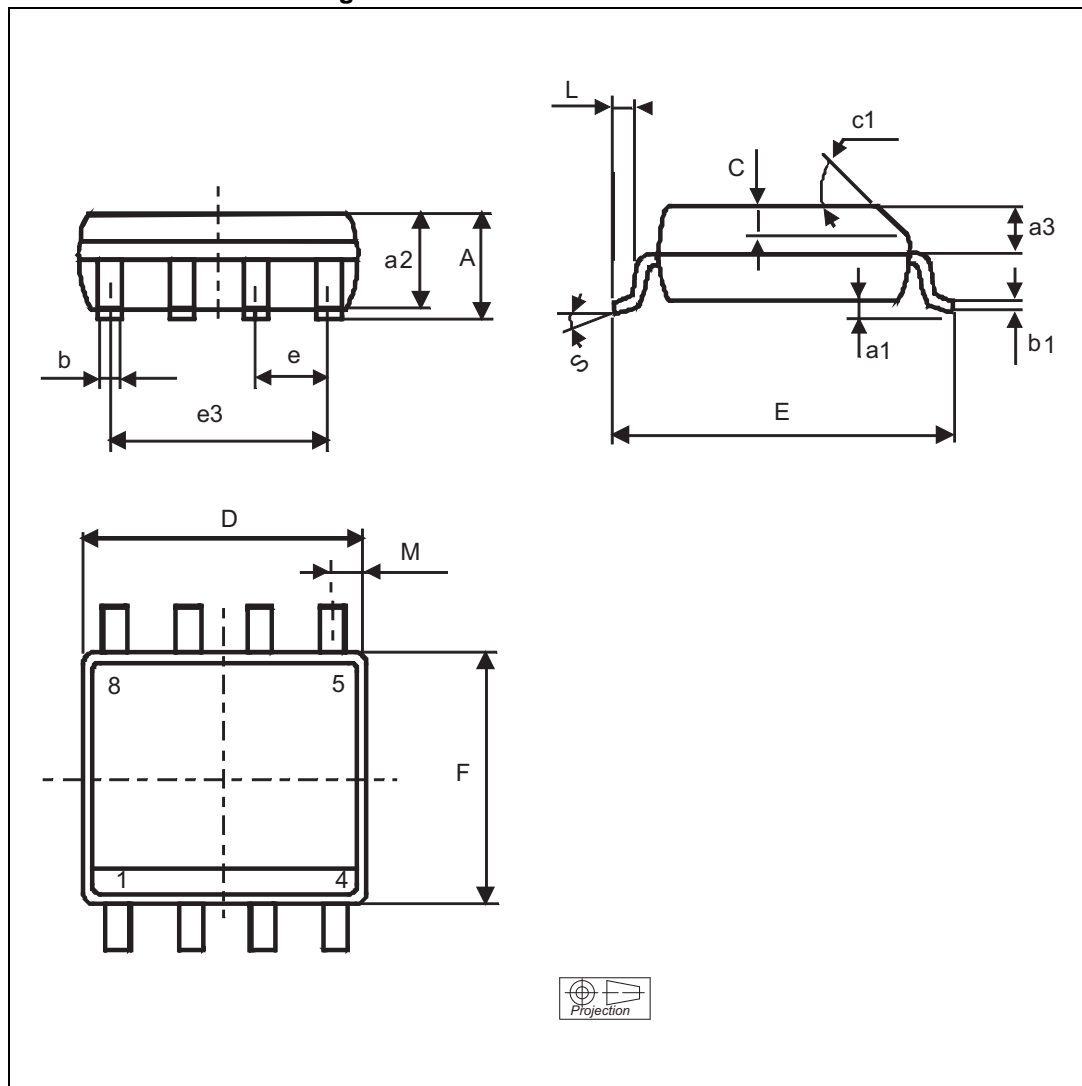
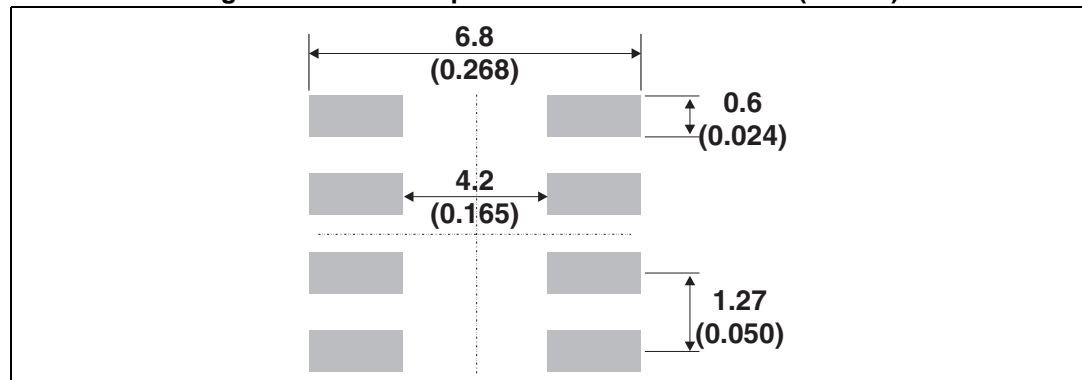


Table 8. SO-8 dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.069
A1	0.1		0.25	0.004		0.010
A2	1.25			0.049		
b	0.28		0.48	0.011		0.019
C	0.17		0.23	0.007		0.009
D	4.80	4.90	5.00	0.189	0.193	0.197
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e		1.27			0.050	
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
L1		1.04			0.041	
k°	0		8	0		8
ccc			0.10			0.004

Figure 10. SO-8 footprint measurements in mm (inches)



4 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
LCP1521S	CP152S	SO-8	0.078 g	100	Tube
LCP1521SRL ⁽¹⁾	CP152S			2500	Tape and reel

1. Preferred device

5 Revision history

Table 10. Document revision history

Date	Revision	Changes
20-Nov-2009	1	First issue.
23-Feb-2012	2	Standardized nomenclature for Gn.
15-Nov-2013	3	Updated Figure 10 .

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